

**COMPLETE LISTING OF CLAIMS
IN ASCENDING ORDER WITH STATUS INDICATOR**

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1. (Currently Amended) An adhesive resin composition comprising a mixture of a liquid matrix resin and a ferrite powder, said liquid matrix resin containing at least one of the following ingredients (A) and (B):

—(A) a polyamic acid; and

—(B) a resin having an imide bond, being capable of an addition reaction with an amine or capable of self-polymerization, and being capable of dissolving in an organic solvent which becomes a polyimide resin after curing.

2. (Cancelled)

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3. (Currently Amended) An adhesive resin composition according to claim 1 ~~or claim 2~~, wherein 200 to 1500 parts by weight of said ferrite powder is contained in said adhesive resin composition relative to 100 parts by weight of a resin ingredient in said liquid matrix resin.

4. (Original) An adhesive resin composition according to claim 3, wherein said ferrite powder has a mean grain size from 0.01 mm to 5 mm.

5. (Currently Amended) An adhesive resin composition according to claim 1 ~~or claim 2~~ wherein said ferrite powder has a mean grain size from 0.01 mm to 5 mm.

6. (Currently Amended) A method of producing an adhesive resin composition, comprising the step of mixing a ferrite powder with a liquid matrix resin containing at least one of the following ingredients (A) and (B):

—(A) a polyamic acid resin; and

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~~—(B) a resin having an imide bond, being capable of an addition reaction with an amine or capable of self-polymerization, and being capable of dissolving in an organic solvent which becomes a polyimide resin after curing.~~

7. (Original) A method according to claim 6, wherein said ferrite powder is mixed with said liquid matrix resin while grinding said ferrite powder using a forced-agitating grinder with a grinding media.

8. (Currently Amended) A chip coil component comprising:

a coil unit having at least one coil conductor pattern;

a pair of magnetic substrates sandwiching said coil unit; and

an outer electrode being electrically connected with said coil conductor pattern,

wherein said coil unit is bonded to said magnetic substrates to thereby allow said magnetic substrates and said adhesive resin composition to form a closed magnetic circuit structure,

said coil unit and magnetic substrates being bonded with an adhesive resin composition comprising a mixture of a liquid matrix resin and a ferrite powder, said liquid matrix resin containing at least one of the following ingredients (A) and (B):

—(A) a polyamic acid; and

~~—(B) a resin having an imide bond, being capable of an addition reaction with an amine or capable of self-polymerization, and being capable of dissolving in an organic solvent which becomes a polyimide resin after curing.~~

9. (Original) A chip coil component according to claim 8, wherein said liquid matrix resin becomes a polyimide resin after curing.

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10. (Currently Amended) A chip coil component according to claim 8 or claim 9, wherein 200 to 1500 parts by weight of said ferrite powder is contained in said adhesive resin composition relative to 100 parts by weight of a resin ingredient in said liquid matrix resin.

11 (Original) A chip coil component according to claim 8, further comprising a through hole extending through said coil unit between said pair of magnetic substrates, said through hole containing said adhesive resin composition and thereby forming part of said closed magnetic circuit structure.

12. (New) An adhesive resin composition according to claim 1, wherein the polyamic acid is the reaction product of a tetracarboxylic anhydride and a diamine.

13. (New) An adhesive resin composition according to claim 12, wherein the tetracarboxylic anhydride is at least one selected from the group consisting of pyromellitic anhydride, biphenyltetracarboxylic anhydride, benzophenonetetra-carboxylic anhydride, and ethylenetetracarboxylic anhydride.

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14. (New) An adhesive resin composition according to claim 12, wherein the diamine is at least one selected from the group consisting of diaminodiphenyl ether, diaminodiphenyl sulfone, diaminodiphenylmethane, and aminobenzylamine.

15. (New) An adhesive resin composition according to claim 6, wherein the polyamic acid is the reaction product of a tetracarboxylic anhydride and a diamine.

16. (New) An adhesive resin composition according to claim 15, wherein the tetracarboxylic anhydride is at least one selected from the group consisting of pyromellitic anhydride, biphenyltetracarboxylic anhydride, benzophenonetetra-carboxylic anhydride, and ethylenetetracarboxylic anhydride.

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17. (New) An adhesive resin composition according to claim 15, wherein the diamine is at least one selected from the group consisting of diaminodiphenyl ether, diaminodiphenyl sulfone, diaminodiphenylmethane, and aminobenzylamine.

18. (New) An adhesive resin composition according to claim 8, wherein the polyamic acid is the reaction product of a tetracarboxylic anhydride and a diamine.

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19. (New) An adhesive resin composition according to claim 18, wherein the tetracarboxylic anhydride is at least one selected from the group consisting of pyromellitic anhydride, biphenyltetracarboxylic anhydride, benzophenonetetra-carboxylic anhydride, and ethylenetetracarboxylic anhydride.

20. (New) An adhesive resin composition according to claim 18, wherein the diamine is at least one selected from the group consisting of diaminodiphenyl ether, diaminodiphenyl sulfone, diaminodiphenylmethane, and aminobenzylamine.